

ISL78307

40V, Low Quiescent Current, 50mA Linear Regulator for Automotive Applications

FN7658  
Rev.4.00  
Aug 8, 2019

The [ISL78307](#) is a high voltage, low quiescent current linear regulator ideally suited for “always-on” and “keep alive” automotive applications. The ISL78307 operates from an input voltage of +6V to +40V under normal operating conditions and operates down to +3V under a cold crank. It consumes only 18μA of quiescent current at no load on the adjustable version.

The ISL78307 is available in fixed 3.3V, 5V, and adjustable output voltage (2.5V to 12V) options. It features an EN pin that can be used to put the device into a low-quiescent current shutdown mode where it draws only 1.8μA of supply current. The device features over-temperature shutdown and current limit protection.

The ISL78307 is AEC-Q100 qualified. It is rated across the -40 °C to +125 °C automotive temperature range and is available in an 8 Ld EPSOIC with exposed pad package.

**Applications**

- Automotive
- Industrial
- Telecom

**Features**

- Optimized for “always-on” automotive applications
- 18μA typical quiescent current
- Ensured 50mA output current
- Operates through cold crank down to 3V
- 40V tolerant logic level (TTL/CMOS) enable input
- 1.8μA of typical shutdown current
- Low dropout voltage of 120mV at 50mA
- Fixed +3.3V, +5.0V and adjustable output voltage options
- Stable operation with 10μF output capacitor
- Thermal shutdown and current limit protection
- -40 °C to +125 °C operating temperature range
- Thermally enhanced 8 Ld exposed pad SOIC package
- [AEC-Q100](#) qualified
- 6kV ESD HBM rated
- Pb-free (RoHS compliant)

**Related Literature**

For a full list of related documents, visit our website

- [ISL78307](#) product page

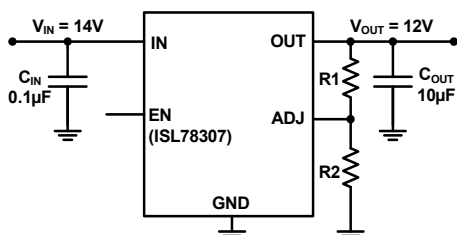


FIGURE 1. TYPICAL APPLICATION - ADJ VERSION

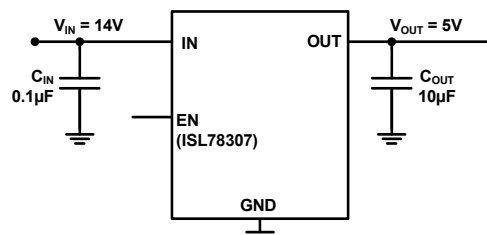


FIGURE 2. TYPICAL APPLICATION - FIXED VERSION

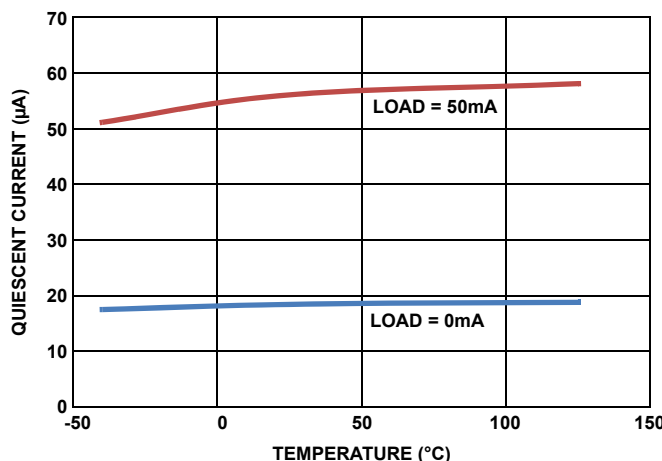
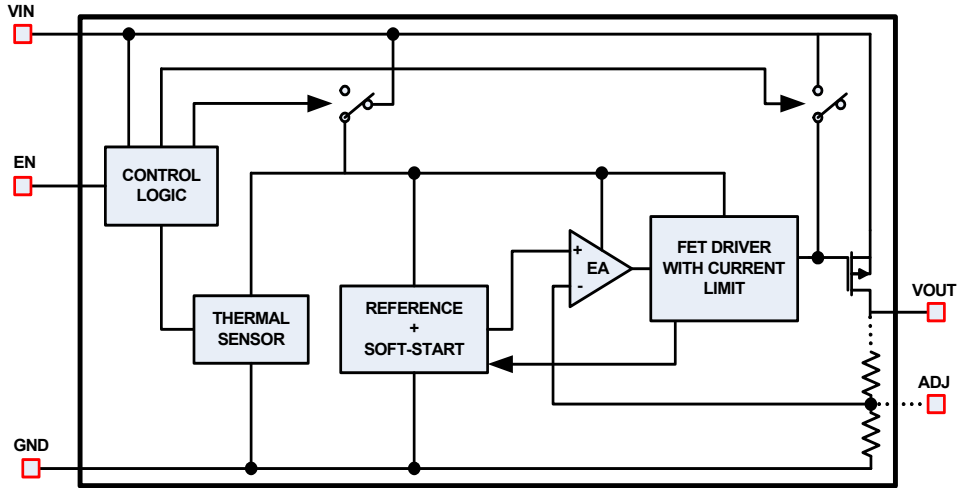


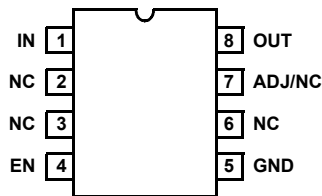
FIGURE 3. QUIESCENT CURRENT vs LOAD CURRENT (ADJ VERSION AT UNITY GAIN). V<sub>IN</sub> = 14V

## Block Diagram



## Pin Configuration

ISL78307  
(8 LD EPOIC)  
TOP VIEW



## Pin Descriptions

PIN NUMBER	PIN NAME	DESCRIPTION
1	IN	Input voltage pin. A minimum 0.1µF X5R/X7R capacitor is required for proper operation.
2, 3, 6	NC	Pins have internal termination and can be left unconnected. Connection to ground is optional.
4	EN	High on this pin enables the device.
5	GND	Ground pin.
7	ADJ/NC	In the adjustable output voltage option, this pin is connected to the external feedback resistor divider which sets the LDO output voltage. In the 3.3V and 5V options, this pin is not used and can be connected to ground.
8	OUT	Regulated output voltage. A 10µF X5R/X7R output capacitor is required for stability.
	EPAD	It is recommended to solder the EPAD to the ground plane.

## Ordering Information

PART NUMBER (Notes 2, 3)	PART MARKING	TEMP. RANGE (°C)	ENABLE PIN	OUTPUT VOLTAGE (V)	TAPE AND REEL (UNITS) (Note 1)	PACKAGE (RoHS Compliant)	PKG. DWG. #
ISL78307FBEAZ	78307 FBEAZ	-40 to +125	Yes	3.3	-	8 Ld EPSOIC	M8.15B
ISL78307FBEAZ-T	78307 FBEAZ	-40 to +125	Yes	3.3	2.5k	8 Ld EPSOIC	M8.15B
ISL78307FBEAZ-T7A	78307 FBEAZ	-40 to +125	Yes	3.3	250	8 Ld EPSOIC	M8.15B
ISL78307FBEBZ	78307 FBEBZ	-40 to +125	Yes	5.0	-	8 Ld EPSOIC	M8.15B
ISL78307FBEBZ-T	78307 FBEBZ	-40 to +125	Yes	5.0	2.5k	8 Ld EPSOIC	M8.15B
ISL78307FBEBZ-T7A	78307 FBEBZ	-40 to +125	Yes	5.0	250	8 Ld EPSOIC	M8.15B
ISL78307FBECZ	78307 FBECZ	-40 to +125	Yes	ADJ	-	8 Ld EPSOIC	M8.15B
ISL78307FBECZ-T	78307 FBECZ	-40 to +125	Yes	ADJ	2.5k	8 Ld EPSOIC	M8.15B
ISL78307FBECZ-T7A	78307 FBECZ	-40 to +125	Yes	ADJ	250	8 Ld EPSOIC	M8.15B

### NOTES:

1. See [TB347](#) for details about reel specifications.
2. These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
3. For Moisture Sensitivity Level (MSL), see the [ISL78307](#) device page. For more information about MSL, see [TB363](#).

## Absolute Maximum Ratings

Supply Voltage, VCC	+45V
IN Pin to GND Voltage	GND - 0.3V to VCC
OUT Pin to GND Voltage	GND - 0.3V to 16V
EN Pin to GND Voltage	GND - 0.3V to VCC
Output Short-Circuit Duration	Indefinite
ESD Rating	
Human Body Model (Tested per JESD22-A114E)	6kV
Machine Model (Tested per JESD-A115-A)	350V
Charge Device Model (Tested per AEC-Q100-011)	2.2kV
Latch-Up (Tested per JESD78B; Class II, Level A)	100mA

## Thermal Information

Thermal Resistance (Typical)	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
8 Ld EPSON Package (Notes 4, 5)	50	9
Maximum Junction Temperature	+150°C	
Maximum Storage Temperature Range	-65°C to +175°C	
Pb-Free Reflow Profile	see <a href="#">TB493</a>	

## Recommended Operating Conditions

Ambient Temperature Range	-40°C to +125°C
IN Pin to GND Voltage	+3V to +40V
OUT Pin to GND Voltage	+2.5V to +12V
EN Pin to GND Voltage	.0V to +40V

**CAUTION:** Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

### NOTES:

- $\theta_{JA}$  is measured in free air with the component mounted on a high-effective thermal conductivity test board with “direct attach” features. See [TB379](#).
- For  $\theta_{JC}$ , the “case temp” location is the center of the exposed metal pad on the package underside.

## Electrical Specifications

Recommended Operating Conditions, unless otherwise noted.  $V_{IN} = 14V$ ,  $I_{OUT} = 1mA$ ,  $C_{IN} = 0.1\mu F$ ,  $C_{OUT} = 10\mu F$ ,  $T_A = T_J = -40^\circ C$  to  $+125^\circ C$ , unless otherwise noted. Typical specifications are at  $T_A = +25^\circ C$ . **Boldface limits apply across the operating temperature range, -40°C to +125°C.**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT	
Input Voltage Range	$V_{IN}$		<b>6</b>		<b>40</b>	V	
		Cold Crank condition	<b>3</b>		<b>40</b>	V	
Guaranteed Output Current	$I_{OUT}$	$V_{IN} = V_{OUT} + V_{DO}$	<b>50</b>			mA	
Output Voltage	$V_{OUT}$	EN = High $V_{IN} = 14V$ $I_{OUT} = 0.1mA$	3.3V version	<b>3.267</b>	3.3	<b>3.333</b>	V
			5V version	<b>4.950</b>	5	<b>5.050</b>	V
			ADJ pin voltage	<b>1.211</b>	1.223	<b>1.235</b>	V
Line Regulation	$\Delta V_{OUT}/\Delta V_{IN}$	$3V \leq V_{IN} \leq 40V$ $I_{OUT} = 1mA$		0.04	<b>0.115</b>	%	
Load Regulation	$\Delta V_{OUT}/\Delta I_{OUT}$	$V_{IN} = V_{OUT} + V_{DO}$ $I_{OUT} = 100\mu A$ to 50mA		0.25	<b>0.5</b>	%	
Dropout Voltage (Note 6)	$\Delta V_{DO}$	$I_{OUT} = 1mA$ , $V_{OUT} = 3.3V$		10	<b>38</b>	mV	
		$I_{OUT} = 50mA$ , $V_{OUT} = 3.3V$		130	<b>340</b>	mV	
		$I_{OUT} = 1mA$ , $V_{OUT} = 5V$		10	<b>48</b>	mV	
		$I_{OUT} = 50mA$ , $V_{OUT} = 5V$		120	<b>350</b>	mV	
Shutdown Current	$I_{SHDN}$	EN = LOW		1.8	<b>3.64</b>	$\mu A$	
Quiescent Current	IQ	EN = High $V_{IN} = 14V$	$I_{OUT} = 0mA$ , ADJ version, $V_{OUT} = V_{ADJ}$		18	<b>24</b>	$\mu A$
			$I_{OUT} = 1mA$ , ADJ version, $V_{OUT} = V_{ADJ}$		22	<b>42</b>	$\mu A$
			$I_{OUT} = 10mA$ , ADJ version, $V_{OUT} = V_{ADJ}$		34	<b>60</b>	$\mu A$
			$I_{OUT} = 50mA$ , ADJ version, $V_{OUT} = V_{ADJ}$		56	<b>82</b>	$\mu A$
			$I_{OUT} = 0$ , 3.3V and 5.0V version		22	<b>28</b>	$\mu A$
			$I_{OUT} = 1mA$ , 3.3V and 5.0V version		27	<b>45</b>	$\mu A$
			$I_{OUT} = 10mA$ , 3.3V and 5.0V version		37	<b>65</b>	$\mu A$
			$I_{OUT} = 50mA$ , 3.3V and 5.0V version		62	<b>90</b>	$\mu A$

**Electrical Specifications** Recommended Operating Conditions, unless otherwise noted.  $V_{IN} = 14V$ ,  $I_{OUT} = 1mA$ ,  $C_{IN} = 0.1\mu F$ ,  $C_{OUT} = 10\mu F$ ,  $T_A = T_J = -40^\circ C$  to  $+125^\circ C$ , unless otherwise noted. Typical specifications are at  $T_A = +25^\circ C$ . **Boldface limits apply across the operating temperature range,  $-40^\circ C$  to  $+125^\circ C$ .** (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
Power Supply Rejection Ratio	PSRR	$f = 100Hz$ ; $V_{in\_ripple} = 500mV_{P,P}$ ; load = 50mA		58		dB
<b>EN FUNCTION</b>						
EN Threshold Voltage	$V_{EN\_H}$	$V_{OUT} = \text{Off to On}$			<b>1.485</b>	V
	$V_{EN\_L}$	$V_{OUT} = \text{On to Off}$	<b>0.935</b>			V
EN Pin Current	$I_{EN}$	$V_{OUT} = 0V$		0.026		$\mu A$
EN to Regulation Time (Note 7)	$t_{EN}$			1.65	<b>1.93</b>	ms
<b>PROTECTION FEATURES</b>						
Output Current Limit	$I_{LIMIT}$	$V_{OUT} = 0V$	<b>60</b>	118		mA
Thermal Shutdown	$T_{SHDN}$	Junction temperature rising		+165		$^\circ C$
Thermal Shutdown Hysteresis	$T_{HYST}$			+20		$^\circ C$

## NOTES:

- Dropout voltage is defined as  $(V_{IN} - V_{OUT})$  when  $V_{OUT}$  is 2% below the value of  $V_{OUT}$  when  $V_{IN} = V_{OUT} + 3V$ .
- Enable to Regulation is the time the output takes to reach 95% of its final value with  $V_{IN} = 14V$  and EN is taken from  $V_{IL}$  to  $V_{IH}$  in 5ns. For the adjustable versions, the output voltage is set at 5V.
- Parameters with MIN and/or MAX limits are 100% tested at  $+25^\circ C$ , unless otherwise specified. Temperature limits established by characterization and are not production tested.

**Typical Performance Curves**  $V_{IN} = 14V, I_{OUT} = 1mA, V_{OUT} = 5V, T_J = +25^\circ C$  unless otherwise specified.

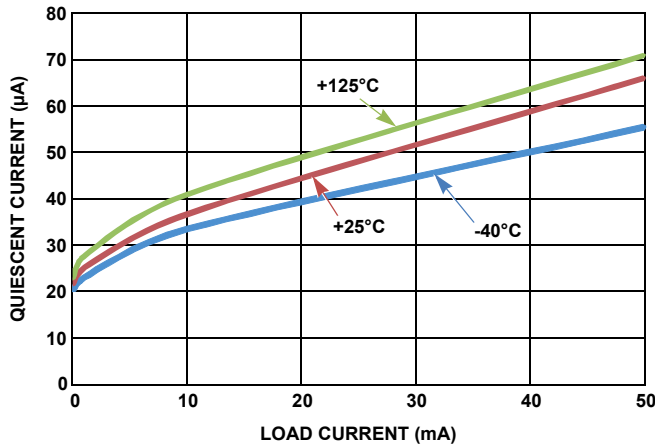


FIGURE 4. QUIESCENT CURRENT vs LOAD CURRENT

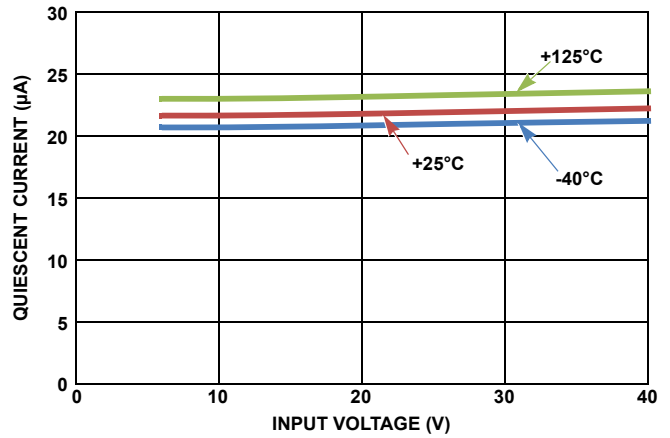


FIGURE 5. QUIESCENT CURRENT vs INPUT VOLTAGE (NO LOAD)

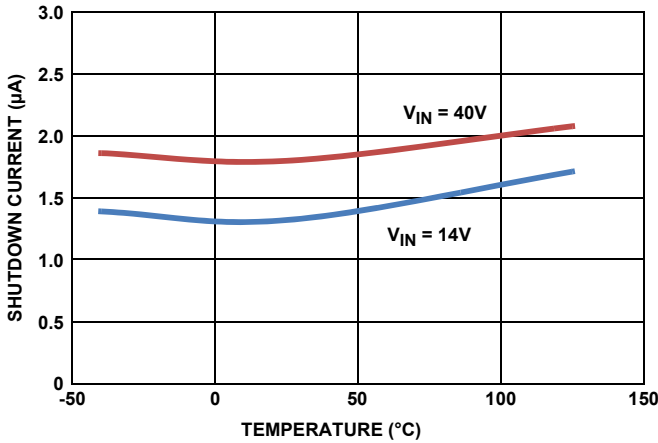


FIGURE 6. SHUTDOWN CURRENT vs TEMPERATURE (EN = 0)

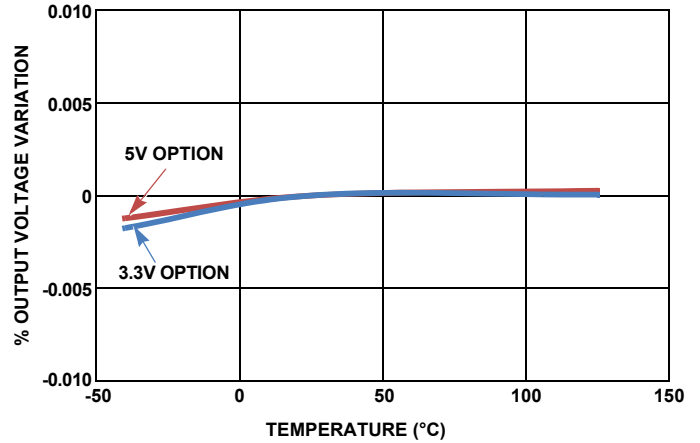


FIGURE 7. OUTPUT VOLTAGE vs TEMPERATURE (LOAD = 50mA)

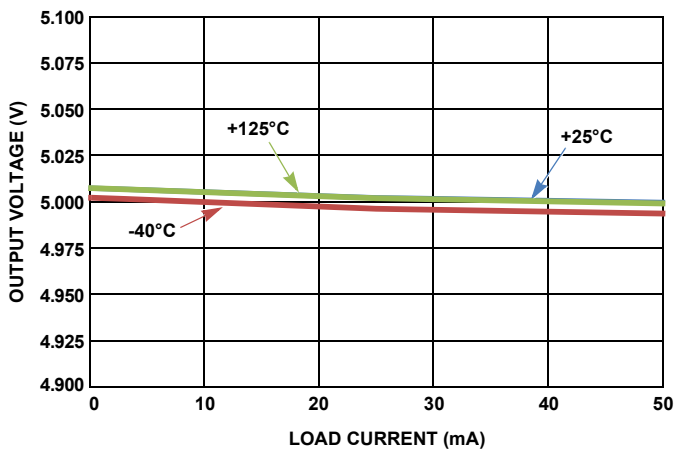


FIGURE 8. OUTPUT VOLTAGE vs LOAD CURRENT

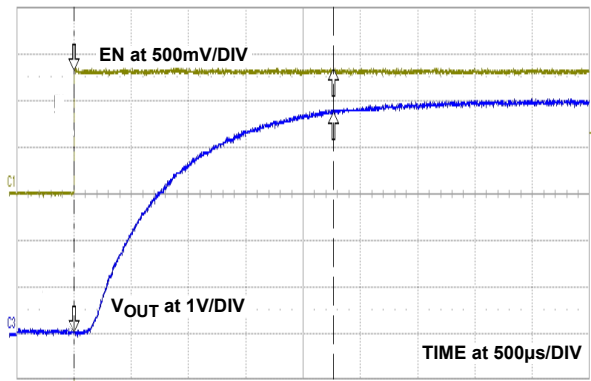


FIGURE 9. START-UP WAVEFORM

**Typical Performance Curves**  $V_{IN} = 14V$ ,  $I_{OUT} = 1mA$ ,  $V_{OUT} = 5V$ ,  $T_J = +25\text{ }^\circ\text{C}$  unless otherwise specified. (Continued)

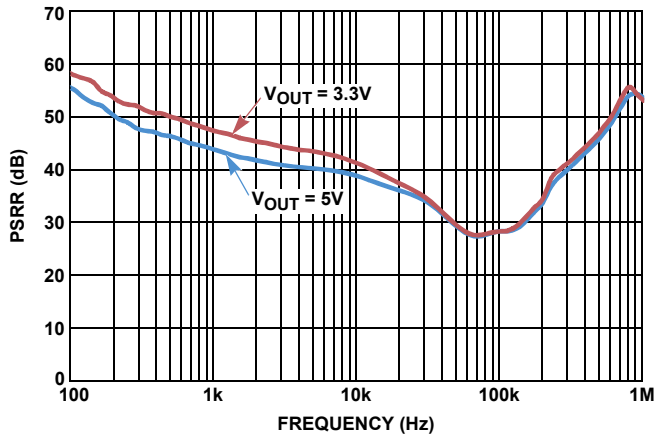


FIGURE 10. POWER SUPPLY REJECTION RATIO (LOAD = 50mA)

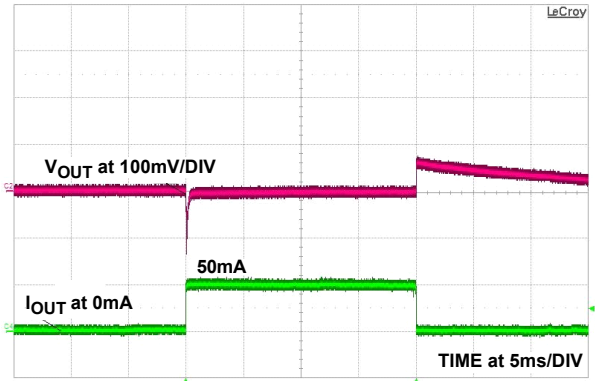


FIGURE 11. LOAD TRANSIENT RESPONSE

## Functional Description

### Functional Overview

The ISL78307 is a high performance, high voltage, low-dropout regulator (LDO) with 50mA sourcing capability. The part is qualified to operate over the  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  automotive temperature range. Featuring ultra-low quiescent current, it makes an ideal choice for “always-on” automotive applications. It works well under a “load-dump condition” where the input voltage could rise up to 40V. The LDO continues to operate down to 3V under a “cold-crank” condition. The device also features current limit and thermal shutdown protection.

### Enable Control

The ISL78307 features an enable pin. When it is pulled low, the IC goes to a shutdown mode. In this condition, the device draws less than  $2\mu\text{A}$ . Driving the pin high turns the device on.

### Current Limit Protection

The ISL78307 has internal current limit functionality to protect the regulator during fault conditions. During current limit, the output sources a fixed amount of current largely independent of the output voltage. If the short or overload is removed from  $V_{\text{OUT}}$ , the output returns to normal voltage regulation mode.

### Thermal Fault Protection

In the event the die temperature exceeds typically  $+165^{\circ}\text{C}$ , the output of the LDO will shut down until the die temperature cools down to typically  $+145^{\circ}\text{C}$ . The level of power dissipated, combined with the ambient temperature and the thermal impedance of the package determine if the junction temperature exceeds the thermal shutdown temperature. See section on “[Power Dissipation](#)”.

## Application Information

### Input and Output Capacitors

For the output, a ceramic capacitor (X5R or X7R) with a capacitance of  $10\mu\text{F}$  is recommended for the ISL78307 to maintain stability. The ground connection of the output capacitor should be routed directly to the GND pin of the device and also placed close to the IC. A minimum of  $0.1\mu\text{F}$  (X5R or X7R) is recommended at the input.

### Output Voltage Setting

For the adjustable version of the ISL78307, the output voltage is programmed using an external resistor divider as shown in [Figure 12](#).

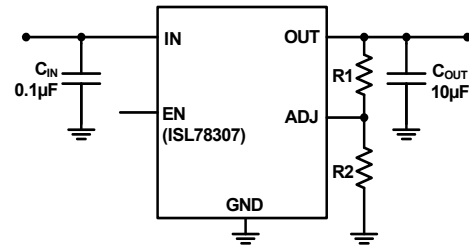


FIGURE 12. ADJUSTABLE VERSION

The output voltage is calculated using [Equation 1](#):

$$V_{\text{OUT}} = 1.223\text{V} \times \left( \frac{R_1}{R_2} + 1 \right) \quad (\text{EQ. 1})$$

### Power Dissipation

The junction temperature must not exceed the range specified in “[Recommended Operating Conditions](#)” on [page 4](#). The power dissipation can be calculated using [Equation 2](#):

$$P_D = (V_{\text{IN}} - V_{\text{OUT}}) \times I_{\text{OUT}} + V_{\text{IN}} \times I_{\text{GND}} \quad (\text{EQ. 2})$$

The maximum allowable junction temperature,  $T_{\text{J(MAX)}}$  and the maximum expected ambient temperature,  $T_{\text{A(MAX)}}$  determine the maximum allowable junction temperature rise ( $\Delta T_{\text{J}}$ ), as shown in [Equation 3](#):

$$\Delta T_{\text{J}} = T_{\text{J(MAX)}} - T_{\text{A(MAX)}} \quad (\text{EQ. 3})$$

To calculate the maximum ambient operating temperature, use the junction-to-ambient thermal resistance ( $\theta_{\text{JA}}$ ) as shown in [Equation 4](#):

$$T_{\text{J(MAX)}} = P_{\text{D(MAX)}} \times \theta_{\text{JA}} + T_{\text{A}} \quad (\text{EQ. 4})$$

### Board Layout Recommendations

A good PCB layout is important to achieve expected performance. Consideration should be taken when placing the components and routing the trace to minimize the ground impedance, and keep the parasitic inductance low. The input and output capacitors should have a good ground connection and be placed as close to the IC as possible. The feedback trace in the adjustable version should be away from other noisy traces. Connect EPAD to the ground plane for better heat dissipation. Thermal vias on the EPAD increase heat dissipation.



## Revision History

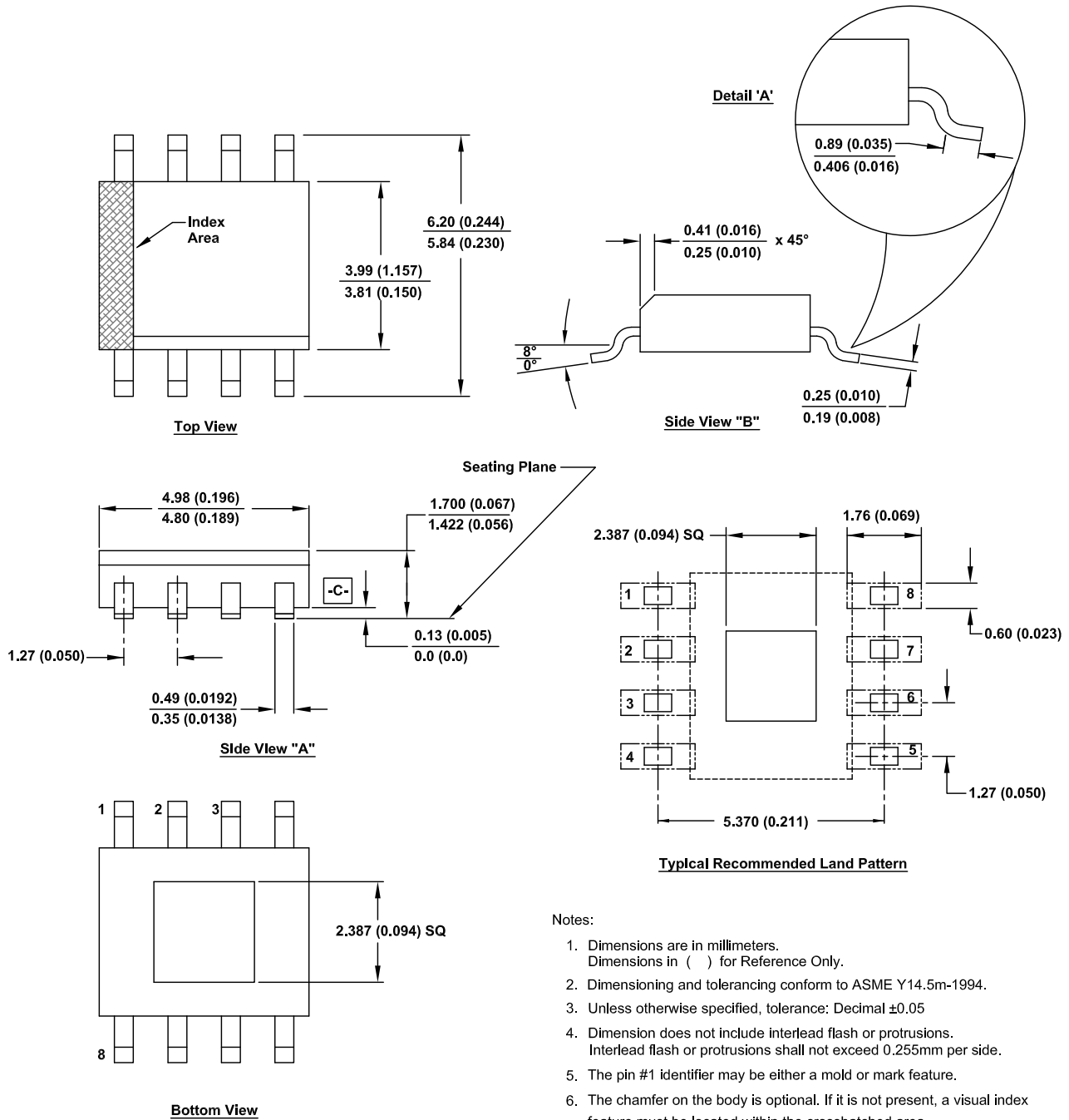
The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest Rev.

DATE	REVISION	CHANGE
Aug 8, 2019	FN6705.4	<p>Updated links throughout document.            Added Related Literature section.            Updated ordering information table by adding tape and reel versions and updating notes.            Removed About Intersil section.            Updated POD to the latest revision changes are as follows:</p> <ul style="list-style-type: none"> <li>-Replace the graphics with standard format (removing the dimension table).</li> <li>-Updated L Millimeter minimum in detail A from 0.41 to 0.406.</li> <li>-Updated the following in the Side View:               <ul style="list-style-type: none"> <li>-Changed total package height Millimeter MIN and MAX values from: 1.43 MIN and 1.68 MAX to: 1.422 MIN and 1.700 MAX and Inches max from 0.066 to 0.067.</li> <li>-Changed A1 Inches MIN from: 0.001 to 0.0, and A1 Millimeters MIN from 0.03 to 0.0</li> </ul> </li> </ul> <p>Updated Disclaimer.</p>
Apr 7, 2015	FN6705.3	<p><a href="#">"Absolute Maximum Ratings" on page 4</a>, Charged device Model(tested per JESD22-C101C)....2.2kV to Charged device Model(tested per AEC-Q100-011).....2.2kV</p>
Dec 7, 2013	FN7658.2	<p>Page 9 - 2nd line of the disclaimer changed from:            "Intersil products are manufactured, assembled and tested utilizing ISO9001 quality systems as noted" to:            "Intersil Automotive Qualified products are manufactured, assembled and tested utilizing TS16949 quality systems as noted".</p>
May 13, 2011	FN7658.1	<p>Page 4, Removed the EN Pin Current MAX spec; added TYP spec of 0.026.</p>

# Package Out Line Drawing

For the most recent package outline drawing, see [M8.15B](#).

M8.15B  
 8 Lead Narrow Body Small Outline Exposed Pad Plastic Package  
 Rev 7, 5/19



**Notes:**

1. Dimensions are in millimeters. Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance: Decimal ±0.05
4. Dimension does not include interlead flash or protrusions. Interlead flash or protrusions shall not exceed 0.255mm per side.
5. The pin #1 identifier may be either a mold or mark feature.
6. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.

## Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
  2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
  3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
  4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
  5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
    - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
    - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
  6. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
  7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
  8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
  9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
  10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
  11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
  12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)

## Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,  
Koto-ku, Tokyo 135-0061, Japan  
[www.renesas.com](http://www.renesas.com)

## Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:  
[www.renesas.com/contact/](http://www.renesas.com/contact/)

## Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.